

N-Channel Dual Gate MOS-Fieldeffect Tetrode, Depletion Mode

Electrostatic sensitive device.
Observe precautions for handling.

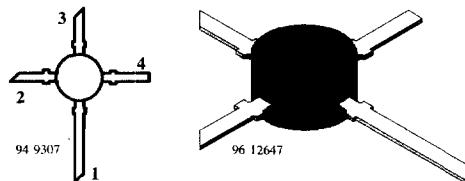


Applications

Input- and mixerstages especially for FM- and VHF TV-tuners up to 300 MHz.

Features

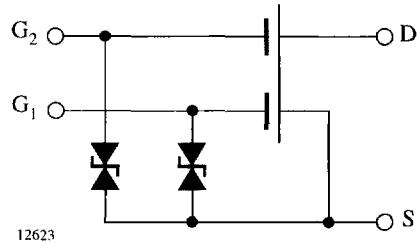
- Integrated gate protection diodes
- High cross modulation performance
- Low noise figure
- High AGC-range
- Low feedback capacitance
- Low input capacitance



BF961 Marking: BF961

Plastic case (TO 50)

1 = Drain, 2 = Source, 3 = Gate 1, 4 = Gate 2



Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Drain source voltage	V _{DS}	20	V
Drain current	I _D	30	mA
Gate 1/gate 2-source peak current	±I _{G1/2SM}	10	mA
Total power dissipation T _{amb} ≤ 60°C	P _{tot}	200	mW
Channel temperature	T _{Ch}	150	°C
Storage temperature range	T _{stg}	-55 to +150	°C

Maximum Thermal Resistance

Parameters	Symbol	Value	Unit
Channel ambient on glass fibre printed board (40 x 25 x 1.5) mm ³ plated with 35 µm Cu	R _{thChA}	450	K/W

Electrical DC Characteristics

T_{amb} = 25°C, unless otherwise specified

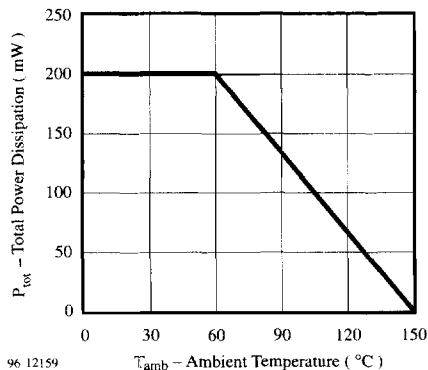
Parameters / Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage I _D = 10 µA, -V _{G1S} = -V _{G2S} = 4 V		V _{(BR)DS}	20			V
Gate 1-source breakdown voltage ±I _{G1S} = 10 mA, V _{G2S} = V _{DS} = 0		±V _{(BR)G1SS}	8		14	V
Gate 2-source breakdown voltage ±I _{G2S} = 10 mA, V _{G1S} = V _{DS} = 0		±V _{(BR)G2SS}	8		14	V
Gate 1-source leakage current ±V _{G1S} = 5 V, V _{G2S} = V _{DS} = 0		±I _{G1SS}			100	nA
Gate 2-source leakage current ±V _{G2S} = 5 V, V _{G1S} = V _{DS} = 0		±I _{G2SS}			100	nA
Drain current V _{DS} = 15 V, V _{G1S} = 0, V _{G2S} = 4 V	BF961 BF961A BF961B	I _{DSS}	4 4 9.5		20 10.5 20	mA mA mA
Gate 1-source cut-off voltage V _{DS} = 15 V, V _{G2S} = 4 V, I _D = 20 µA		-V _{G1S(OFF)}			3.5	V
Gate 2-source cut-off voltage V _{DS} = 15 V, V _{G1S} = 0, I _D = 20 µA		-V _{G2S(OFF)}			3.5	V

Electrical AC Characteristics

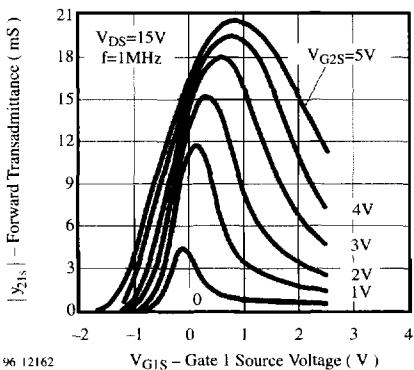
V_{DS} = 15 V, I_D = 10 mA, V_{G2S} = 4 V, f = 1 MHz, T_{amb} = 25°C, unless otherwise specified

Parameters / Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
Forward transadmittance		y _{21s}	12	15		mS
Gate 1-input capacitance		C _{issg1}		3.7		pF
Gate 2-input capacitance V _{G1S} = 0, V _{G2S} = 4 V		C _{issg2}		1.6		pF
Feedback capacitance		C _{rss}		25		fF
Output capacitance		C _{oss}		1.6		pF
Power gain g _S = 2 mS, g _L = 0.5 mS, f = 200 MHz		G _{ps}		20		dB
AGC range V _{G2S} = 4...-2 V, f = 200 MHz		ΔG _{ps}		50		dB
Noise figure g _S = 2 mS, g _L = 0.5 mS, f = 200 MHz		F		1.8	2.5	dB

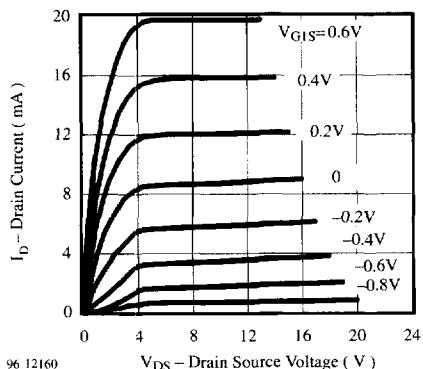
Typical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)



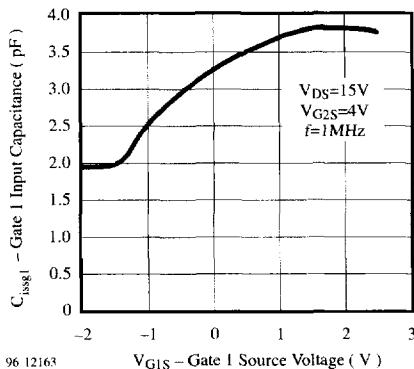
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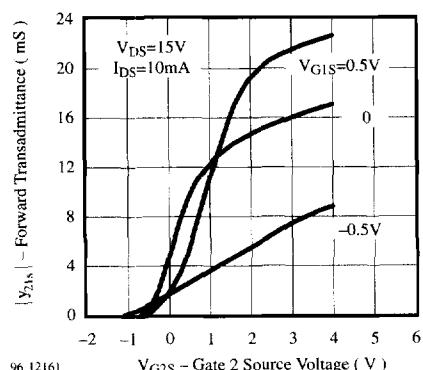
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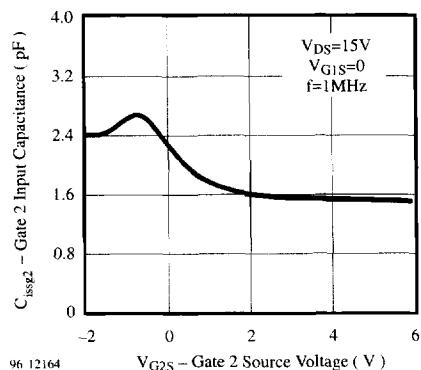
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BF961

TEMIC
Semiconductors

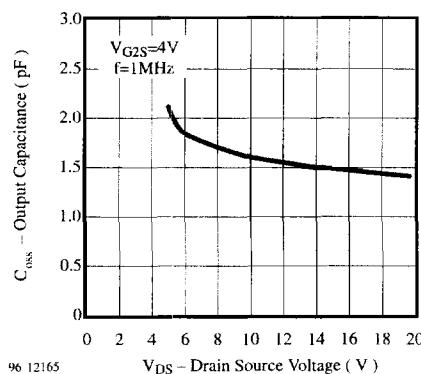


Figure 7. Output Capacitance vs. Drain Source Voltage

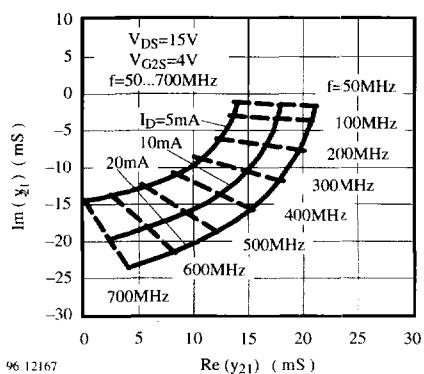


Figure 9. Short Circuit Forward Transfer Admittance

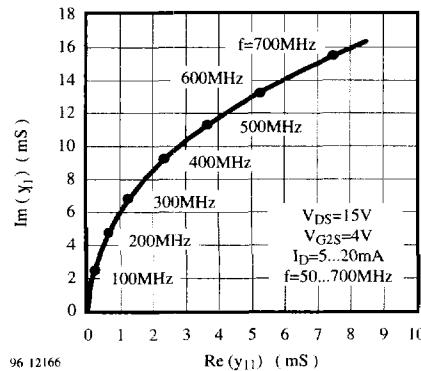


Figure 8. Short Circuit Input Admittance

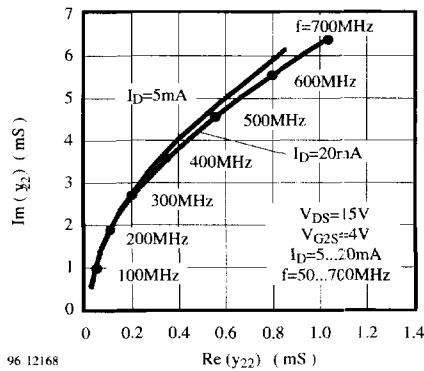


Figure 10. Short Circuit Output Admittance

$V_{DS} = 15$ V; $I_D = 5$ to 20 mA; $V_{G2S} = 4$ V; $Z_0 = 50 \Omega$

S_{11}

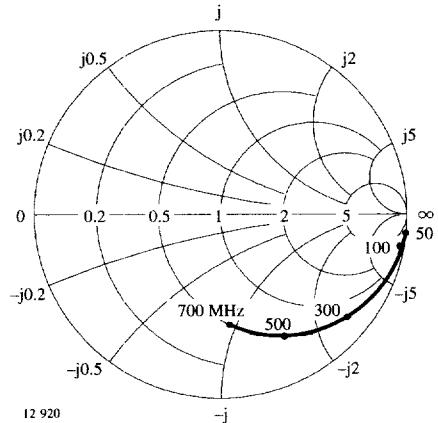


Figure 11. Input reflection coefficient

S_{12}

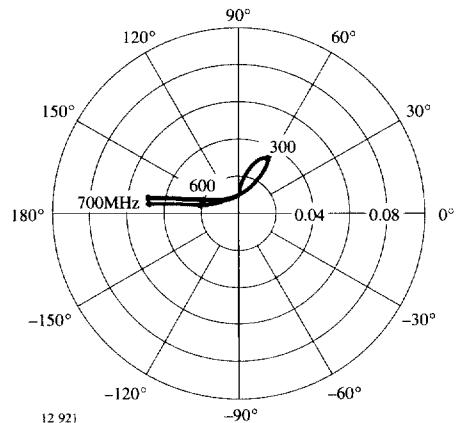


Figure 13. Reverse transmission coefficient

S_{21}

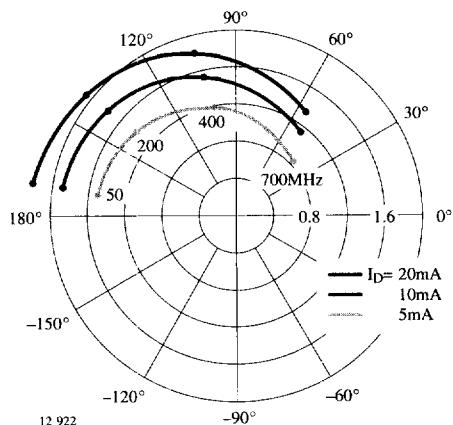


Figure 12. Forward transmission coefficient

S_{22}

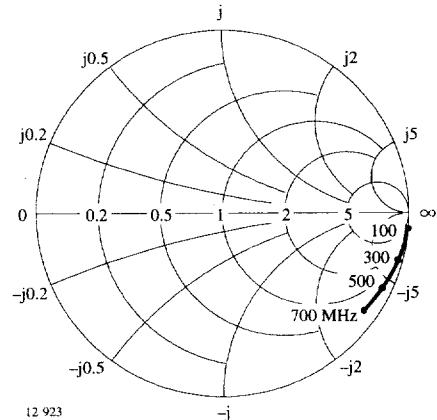
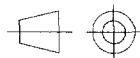
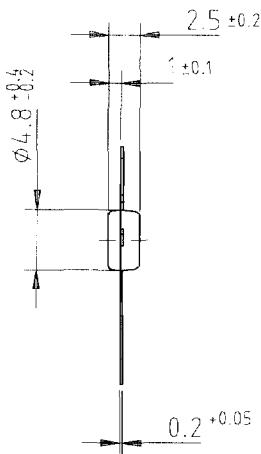
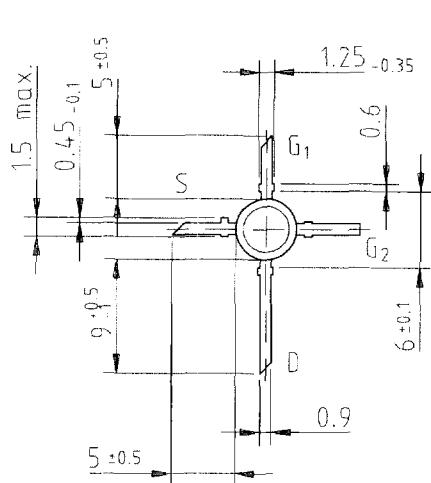


Figure 14. Output reflection coefficient

Dimensions in mm



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technical drawings
according to DIN
specifications